

D137 Jetson Carrier Board (Stacking Design)

Compact Jetson Orin NX / Orin Nano carrier board delivering powerful multi-camera edge AI for UAV and radar systems (GMSL2 & MIPI).



Overview

The Carrier Board is a compact, high-density platform built around the NVIDIA® Jetson Orin™ NX / Orin Nano module. Delivering AI performance in space- and weight-constrained designs. Its small size and robust layout make it well suited for defense-grade unmanned aircraft, radar and other edge systems.

With native GMSL2 and MIPI CSI-2 camera interfaces, the carrier board supports flexible multi-camera configurations, from long-range zoom and low-light sensors to wide-angle situational-awareness views. This enables rich computer-vision workloads such as object detection, tracking, and perception directly at the edge.

Model	D137
NVIDIA Module Compatibility	NVIDIA® Jetson Orin NX / Orin Nano module
Networking	2x Ethernet GH1.25/ 8 pin Wafer (10/100/1000/Gigabit Ethernet)
Display Output	1 x Micro HDMI output (HDMI 1.4, 1080P)
MIPI Camera Inputs	2 x 4 lane MIPI CSI-2, 22 pin FPC 0.5mm Pitch/GMSL Camera Inputs
USB	1x USB 2.0 Type C (For BSP Installation) 3x USB 3.2 Type C
Storage	1x M.2. key M 2230 for NVMe
Expansion Connector	4x UART GH1.25/4pin Wafer 1x Expansion Power Button GH1.25/2pin Wafer 1x Expansion Suspend/Wakeup GH1.25/2pin Wafer 1x Expansion Recovery GH1.25/2pin Wafer 1x CAN Bus GH1.25/ 4 pin wafer 2x SPI GH1.25/6 pin wafer 1x PWMs*4 GH1.25/6pin Wafer 2x I2C (Master) GH1.25/4pin Wafer 1x GPIOs*8 GH1.25/10pin Wafer
RTC Battery	Support RTC battery and Battery Life Monitoring by MCU
Internal Buttons	Power and Recovery and Suspend/Wakeup
Thermal solution	4 pin Fan Wafer solution
Power Input	XT30 DC-IN 12V~50V
Temperature	Operating Temperature -10°C~60°C (Board Level)
Certifications	CE, FCC,VCCI, KC (TBA)
PCB/Electronics Mechanical Info	90mm (L) x 56mm (W) x 30.7mm (H) (Stacking with SOM)
Weight	80g

All specifications are subject to change without prior notice.

